

TQ-M4-VSP

- 于平滑面实施超细微处理之极低粗度电解铜箔(VSP箔)
Very smooth profile ED copper foil (VSP) with very low profile surface treatment.
- 铜箔于全面蚀刻后, 于PI具良好的透视度。
Very good performance for transparency and visibility of PI after etching copper foil.
- 超低粗糙度处理面, 非常适合于高频高速的应用。
Possible to use high frequency application due to very low profile.

用途/Application

- 软性电路板
/Flexible Print Board

构成/Composition



生产地点/Production Site

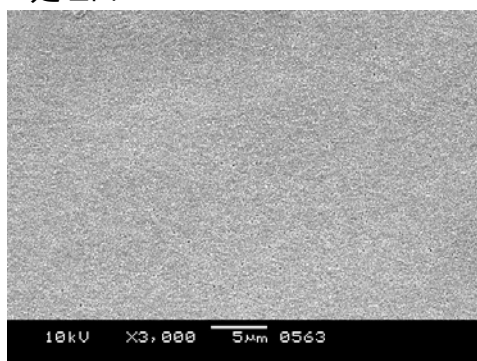
- 日本/Japan

代表性特性数据/Representative data

	μm	Area weight (g/m ²)	Laminate side Rz(μm)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm) ^{@FR-4}
TQ-M4-VSP	12	100	0.6	340	9	0.6
	18	148	0.6	340	12	0.7

※上述表列为代表性数据非保证值
This is representative data, not guaranteed.

处理面/Laminate side



阻剂面/ resist side

